

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10559556
<b>Filing Date:</b>	16-Mar-2006
<b>Title of Invention:</b>	Resin composition for printed wiring board, prepreg, and laminate obtained with the same
<b>First Named Inventor/Applicant Name:</b>	Hidetsugu Motobe
<b>Filer:</b>	Matthew B. Skaggs
<b>Attorney Docket Number:</b>	YOS0024

Filed as Large Entity

### **U.S. National Stage under 35 USC 371 Filing Fees**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				
Extension - 3 months with \$0 paid	1253	1	1110	1110

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Request for continued examination	1801	1	810	810
<b>Total in USD (\$)</b>				<b>1920</b>